



# CMB-S4

*contribution to the front-end readout chain*

## Damien PRÊLE

on behalf of the CMB-S4@IN2P3 : **Horacio Arnaldi**<sup>(1)</sup>, James Bartlett<sup>(1)</sup>, Olivier Bourrion<sup>(4)</sup>, Andrea Catalano<sup>(4)</sup>, **Si Chen**<sup>(1)</sup>, Céline Combet<sup>(4)</sup>, Jacques Delabrouille<sup>(2)</sup>, Elena de laHoz<sup>(2)</sup>, Cyrille Doux<sup>(4)</sup>, Josquin Errard<sup>(1)</sup>, Ken Ganga<sup>(1)</sup>, Xavier Garrido<sup>(3)</sup>, **Manuel Gonzalez**<sup>(1)</sup>, Jean-Christophe Hamilton<sup>(1)</sup>, Sophie Henrot-Versillé<sup>(3)</sup>, Julius Hrivnac<sup>(3)</sup>, Marine Kuna<sup>(4)</sup>, Fabian Lambert<sup>(4)</sup>, Sotiris Loucatos<sup>(1)</sup>, Thibaut Louis<sup>(3)</sup>, Juan Macías Pérez<sup>(4)</sup>, Frédéric Mayet<sup>(4)</sup>, Jérôme Odier<sup>(4)</sup>, Julien Peloton<sup>(4)</sup>, Laurence Perotto<sup>(4)</sup>, **Michel Piat**<sup>(1)</sup>, **Damien Prêle**<sup>(1)</sup>, **Fatah Rarbi**<sup>(4)</sup>, Radek Stompor<sup>(2)</sup>, Jean-Pierre Thermeau<sup>(1)</sup>, Steve Torchinsky<sup>(1)</sup>, **Matthieu Tristram**<sup>(3)</sup>, Christophe Vescovi<sup>(4)</sup>

(1) AstroParticule et Cosmologie (APC)

(2) Centre Pierre Binétruy (CPB)

(3) Laboratoire de Physique de 2 infinis, Irène Joliot-Curie, (IJCLab)

(4) Laboratoire de Physique Subatomique et Cosmologie, (LPSC)



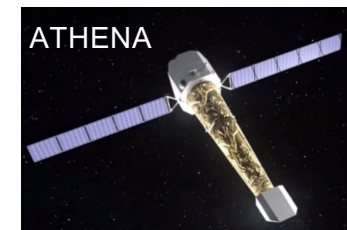
Who Am I

**Damien PRÊLE – APC / Univ. Paris Cité**  
Instrumentalist, VLSI Research Engineer, Project Manager  
**CMB-S4 project and collaboration member**



● **TES/SQUID detection chain projects**

- Instrumentalist for the **QUBIC** ground based telescope for CMB
- Project manager Warm Front End Electronic - WFEE - for X-IFU **ATHENA**
  - Co-Investigator member of the X-IFU instrument
  - ATHENA X-IFU detection chain WG
- IN2P3 instrument leader - **CMB S4** warm analog front-end readout
  - CMB-S4 readout chain WG

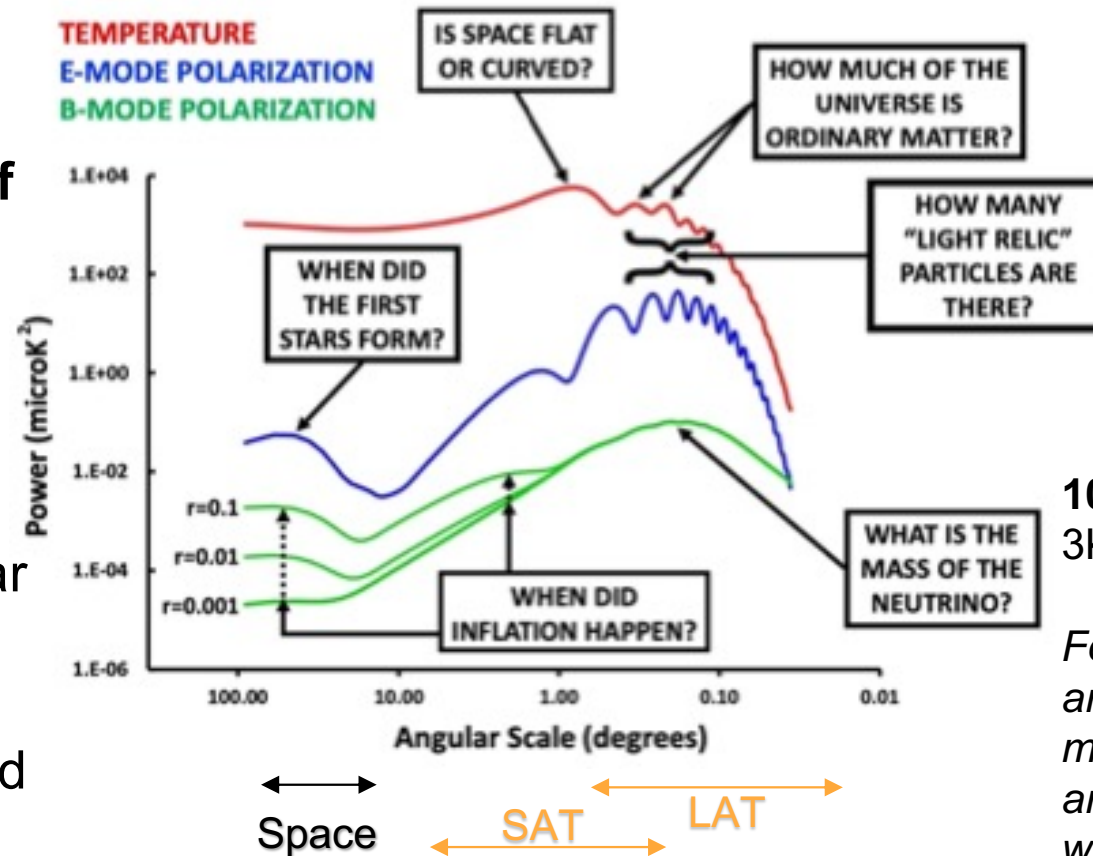


Micro-electronic and BiCMOS SiGe **integrated circuits – ASIC**, Cryo. Semiconductors, Superconductor devices (**SQUID, TES**), Electronic **Noise mitigations and EMI/EMC**, Multiplexing, **Low noise amplifier – LNA, Low noise DACs**, Space technology

# CMB Angular Power Spectra Guide

Weak anisotropy  
Encoded in CMB  
intensity and  
polarization -> **story of  
the origin, evolution,  
and make up of the  
Universe.**

Need to measure the  
anisotropy from angular  
scales of **degrees to  
arcminutes** with  
exquisite sensitivity and  
fidelity.



**10nK fluctuations** on a  
3K in a 300K environment

*Foregrounds mitigation  
and de-lensing requires  
multiple frequency bands  
and broad angular range  
with exceptional sensitivity  
and control of systematics*

# CMB-S4 Instrument Description after AoA

- **500 k deployed detectors** (483344)
- **363 wafers** (All wafers are dichroic except the ULF wafer)
- **3 LATs**
  - 2 x 6 m CD\* Chile > 50% sky
  - 1 x 5 m TMA\*\* Pole ~3% sky)

-> 3x85 tubes<sub>20cm</sub> ; 255 wafers ; 400 k detectors

- 200 TES ULF; 5k LF; 280k MF; 120k HF

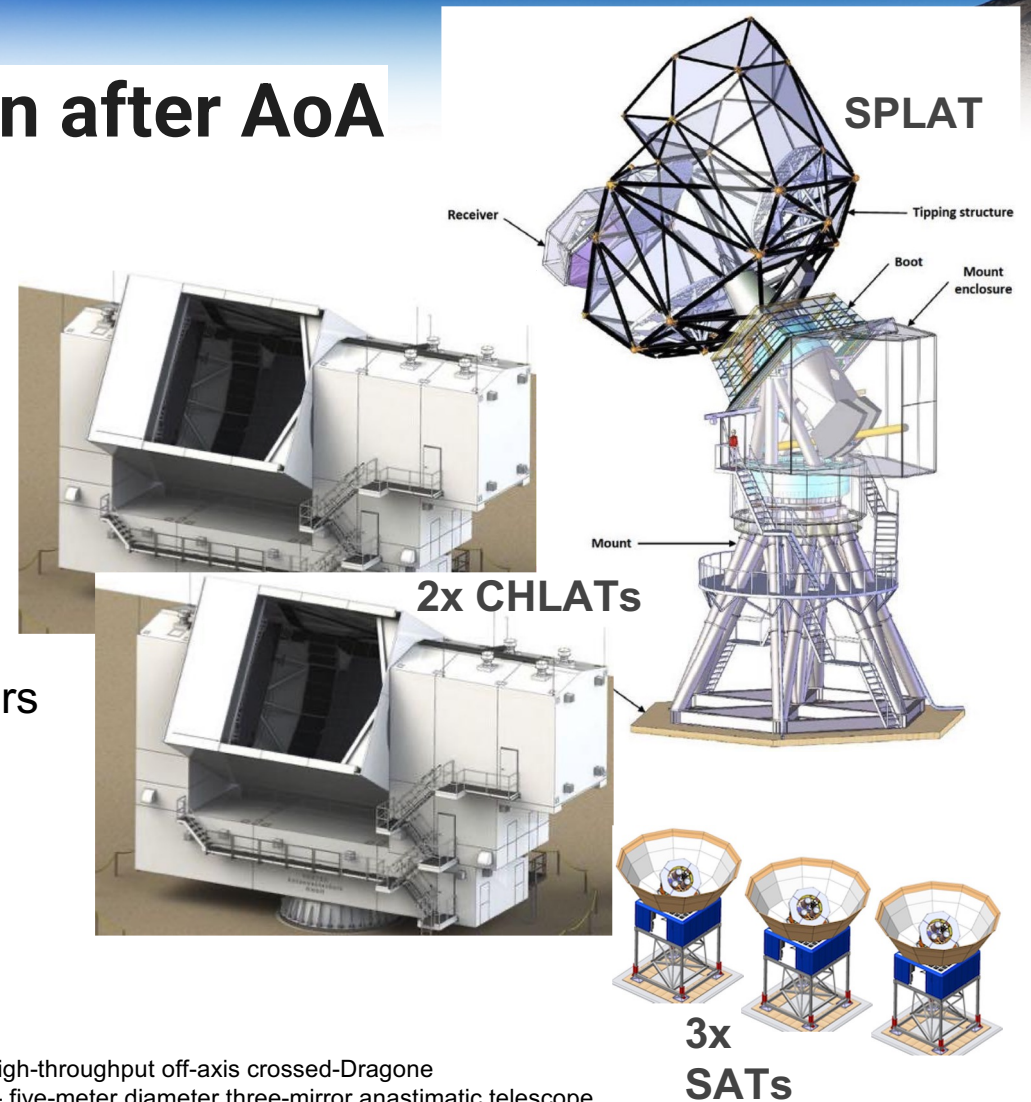
- **3 SATs**

-> 3x3 tubes<sub>50cm</sub>; 108 wafers ; 80 k detectors

- 500 TES LF; 40k MF; 40k HF

\*CD - high-throughput off-axis crossed-Dragone

\*\*TMA - five-meter diameter three-mirror anastigmatic telescope



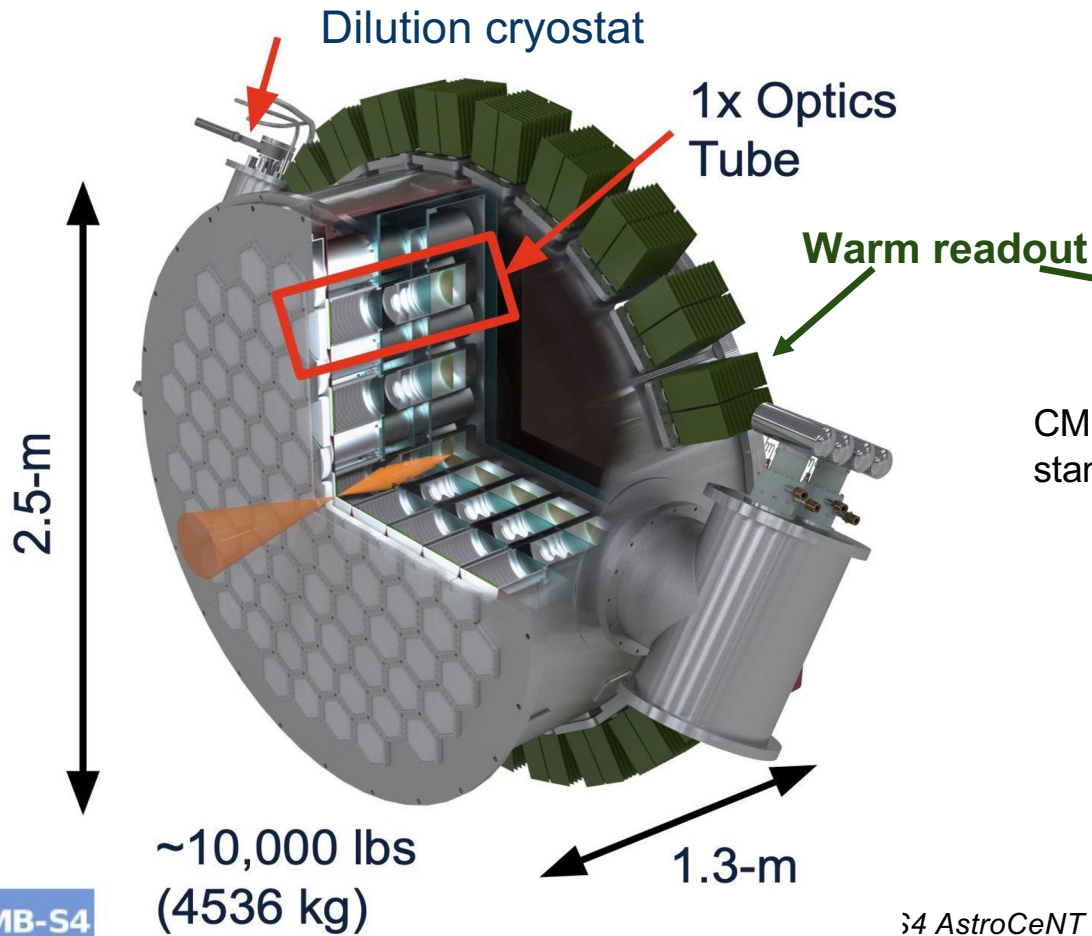
[1] Large Aperture Telescopes Update - M. Niemack

[2] <https://cmb-s4.org/experiment/>

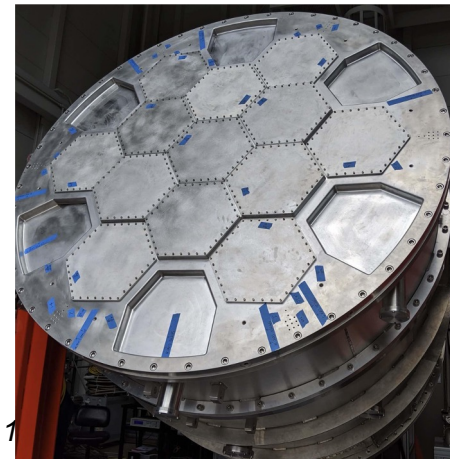
# CMB-S4 LAT and SAT receiver cryostat design

LAT - Large Aperture Telescope

SAT - Small Aperture Telescope

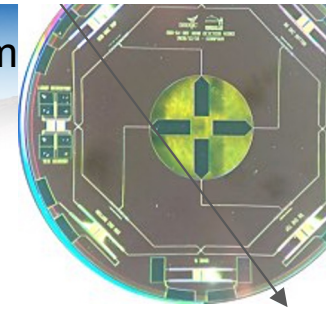


CMB-S4 tubes, detection chain and interfaces must respect S4 standards different from the SAT and LAT SO :

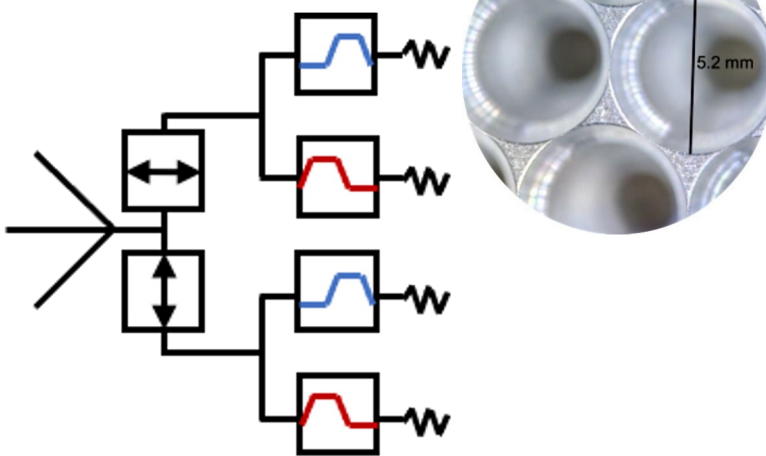
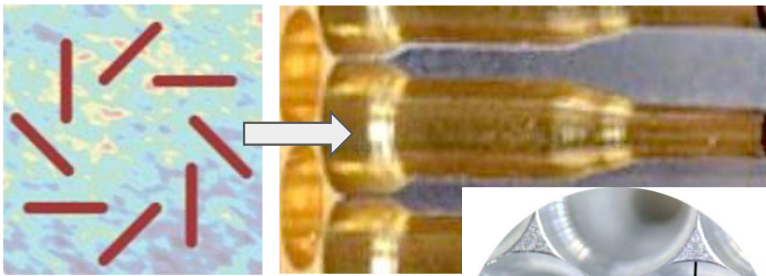


# Polarization sensitive & Multi-Chroic concept

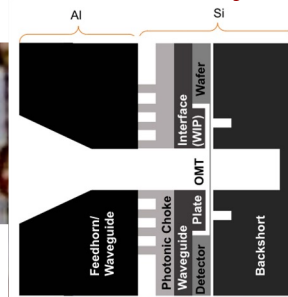
6 mm



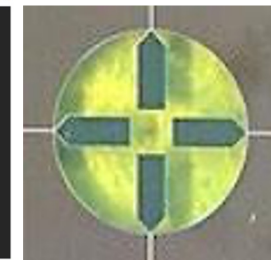
Sky Signal spline-profiled Horn\* array



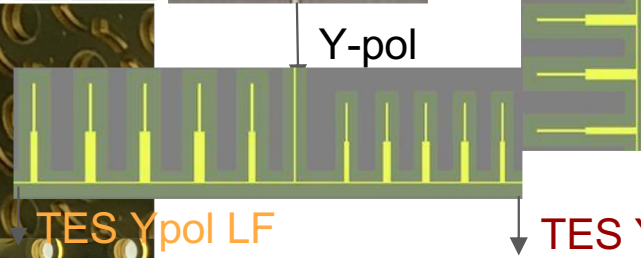
Interfaces layers\*\*



OMT\*\*\*

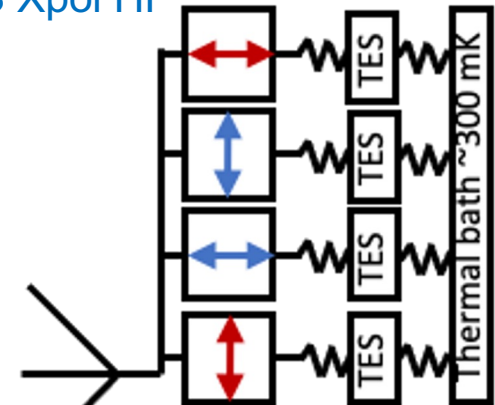


Diplexer\*\*\*\*



TES Xpol HF

TES Xpol HF  
TES Ypol HF



- Sensitive to **polarisation** antenna
- Superconducting **Channelizer** / Diplexer
- End line **dissipator** + Thermalization
- **Bolometer** + Superconducting thermometer

\*Feedhorn dev. and scalability for SO and beyond - S. M. Simon et al.

\*\* Conceptual Design ...for the CMB-S4 survey experiment, D. Barron et al.

\*\*\* JLTP 2022 DOI: 10.1007/s10909-022-02731-x

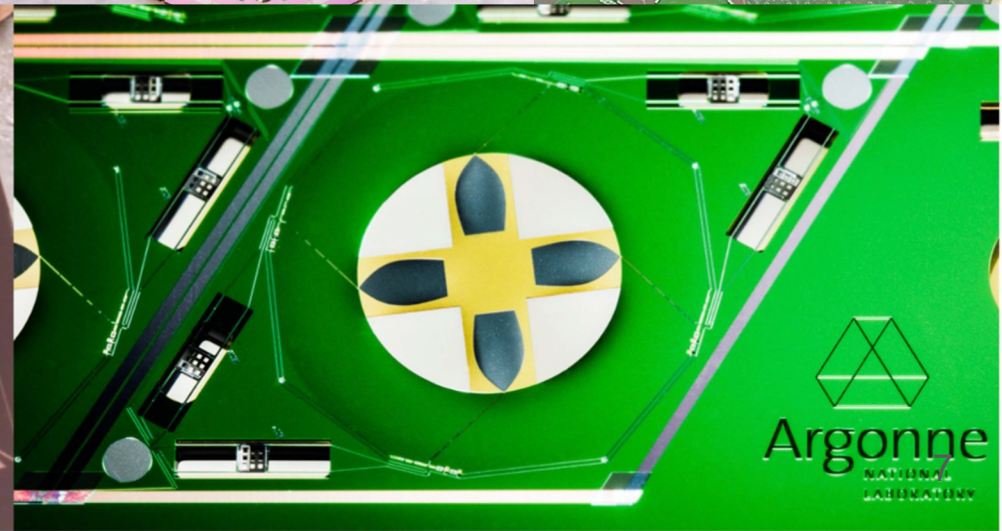
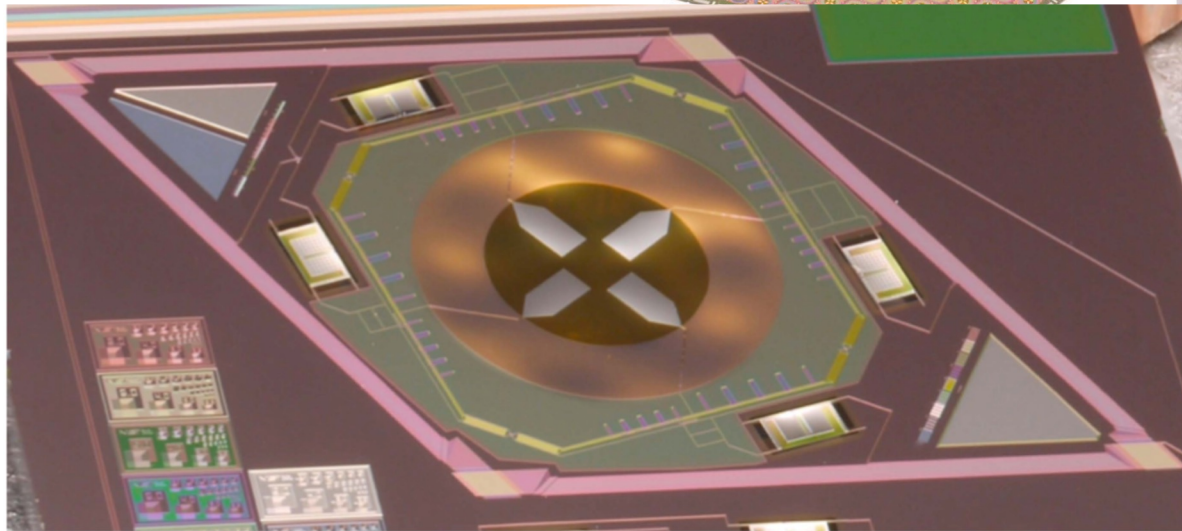
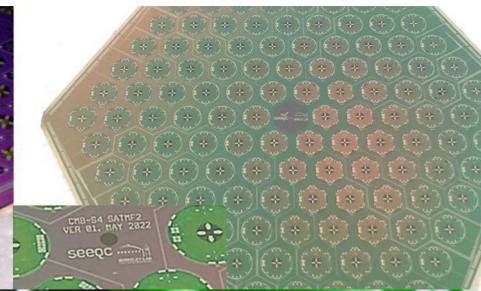
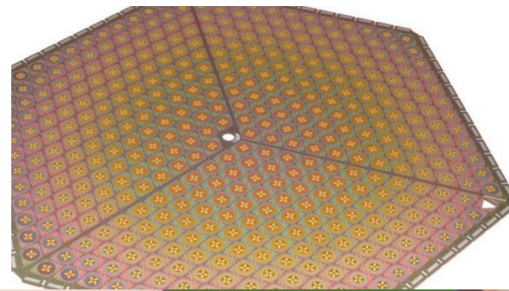
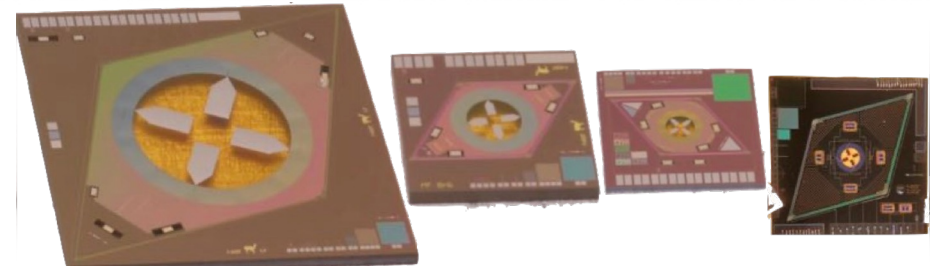
\*\*\*\*Multi-Chroic Detectors for Observing the CMB - A. Traini, M. Piat et al.

# TES : polarisation sensitive + multichroic

6 fabrication sites : NIST, Argonne, UCB, LBNL/SQC, JPL

**SAT** : 30/40 GHz, 85/145 GHz, 95/155 & GHz 225/278 GHz

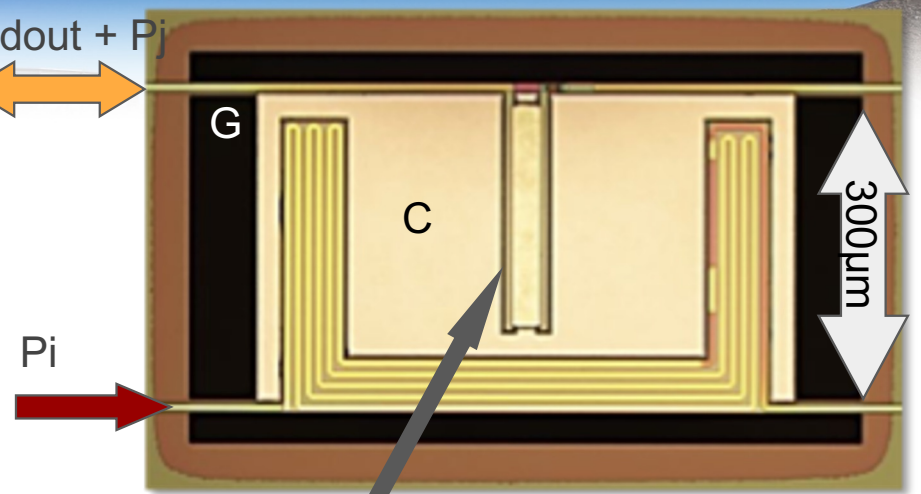
**LAT** : 20 GHz, 30/40 GHz, 90/150 GHz & 225/278 GHz



# Transition Edge Sensors

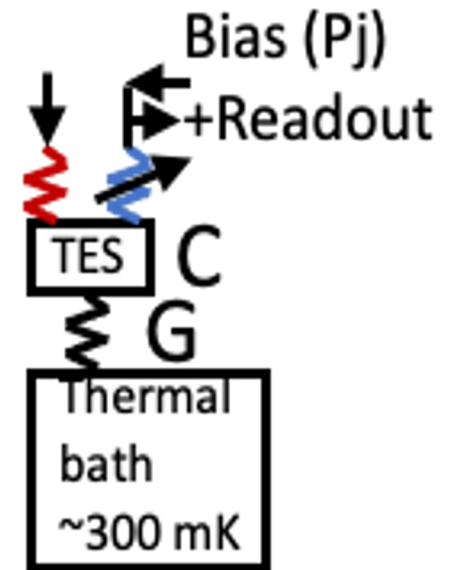
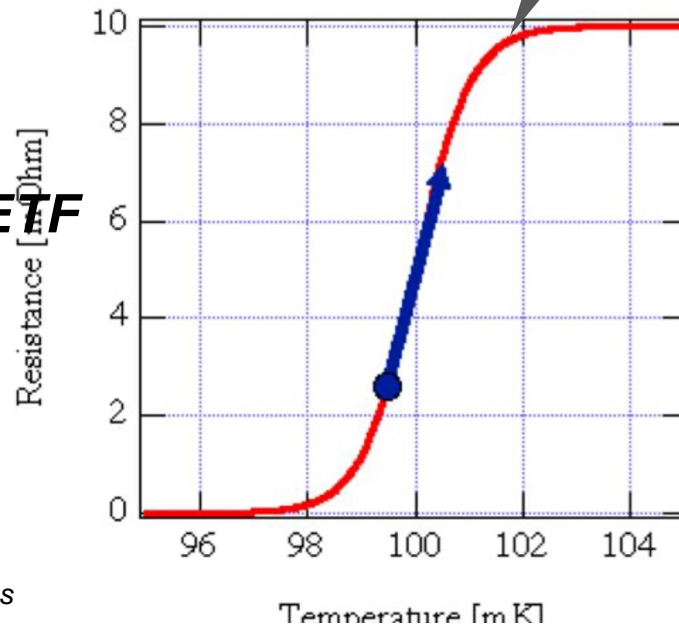
Readout +  $P_J$

- Quadratic detection at the line end
- Bias dissipation  $\rightarrow P_J = V_{\text{bias}}^2 / R_{\text{TES}}$ 
  - auto adjustment in an array @  $T_C$
  - response homogenisation response  
 $\partial I_{\text{TES}} / \partial P_J = 1 / V_{\text{bias}}$
  - Improve time response  $< C/G$



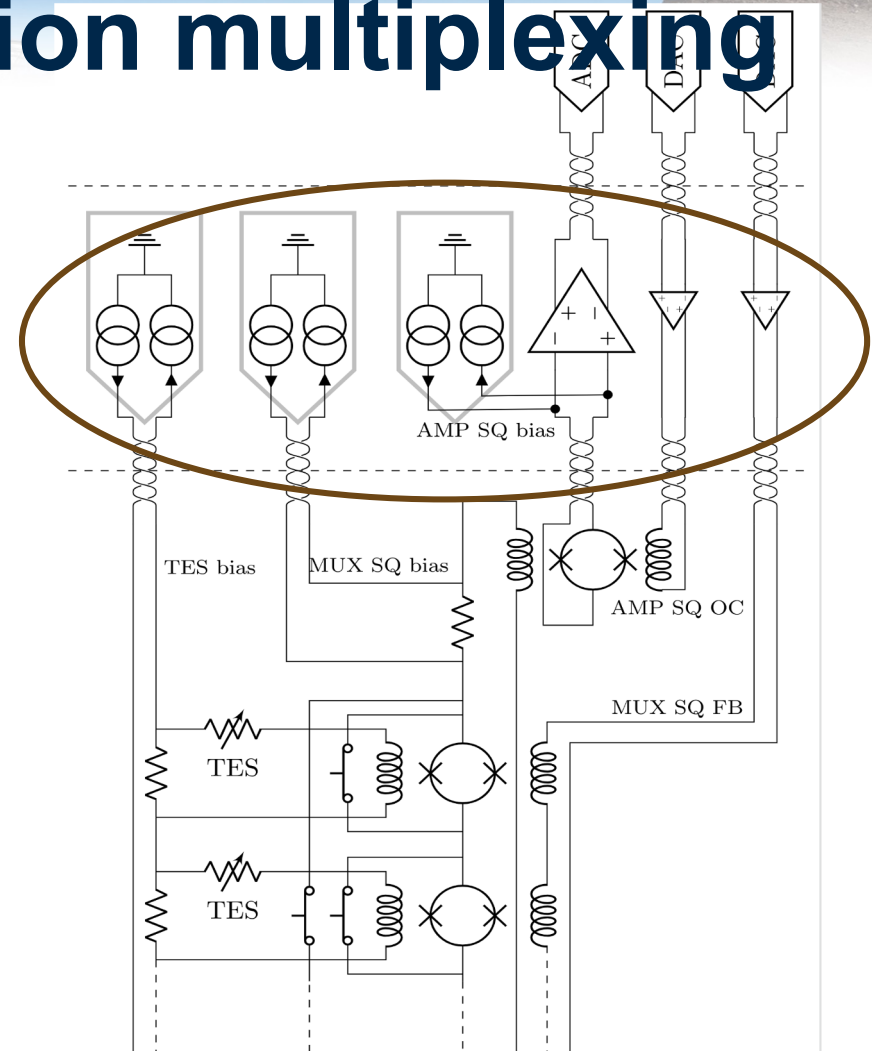
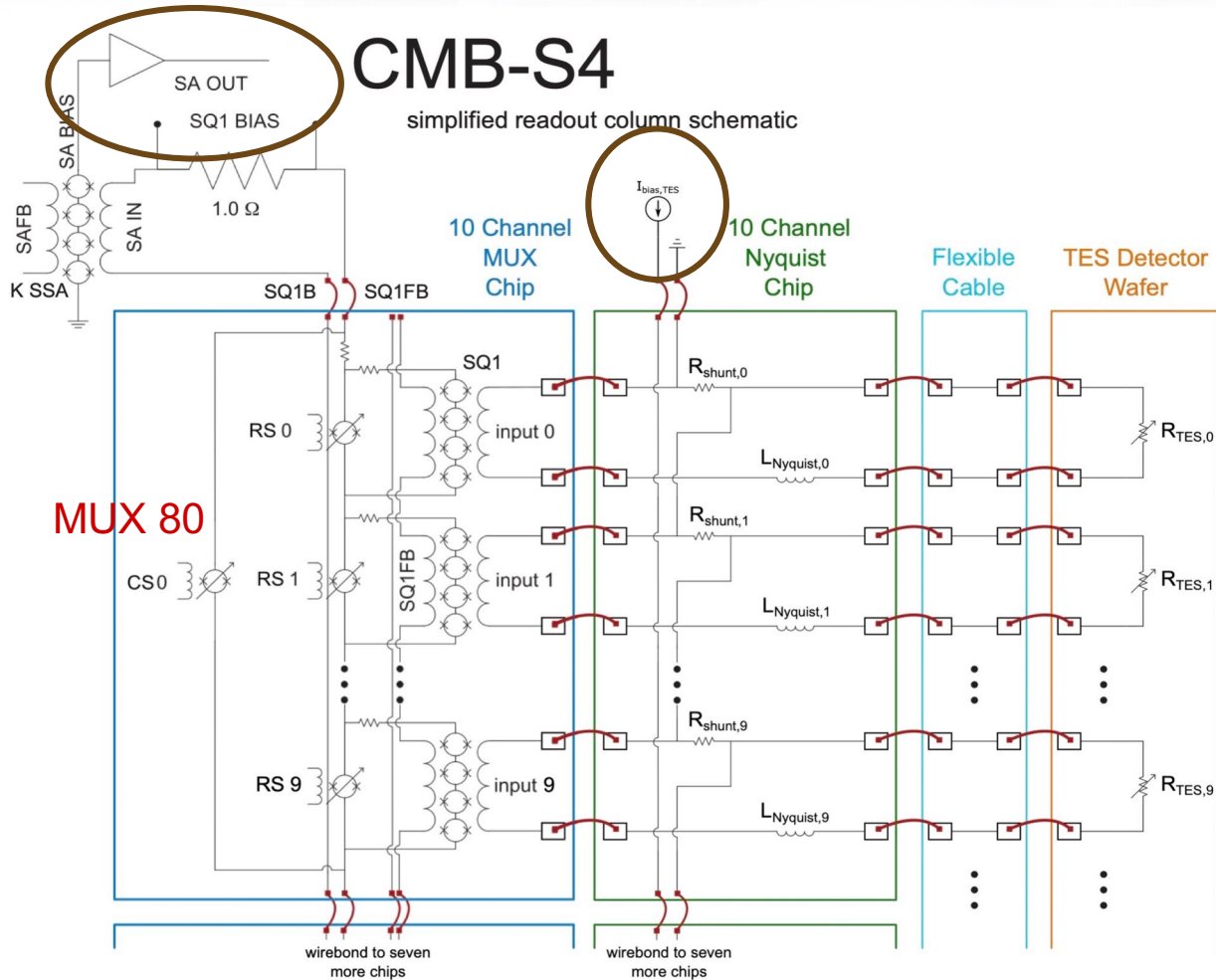
**Strong Electro Thermal Feedback - ETF**

**$\rightarrow$  Voltage biasing = detection transfer function**

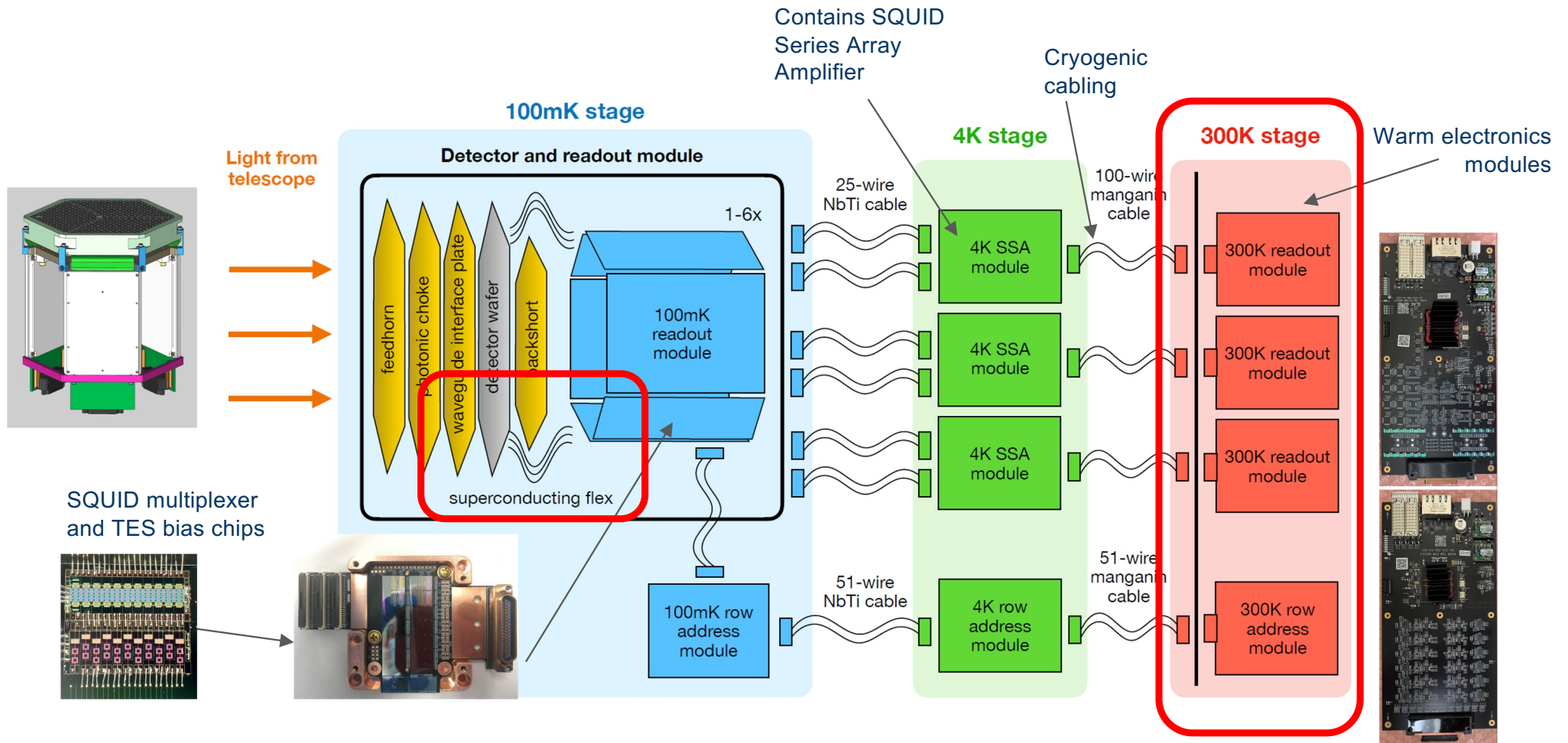




# Readout and Time-division multiplexing



# Readout subsystem

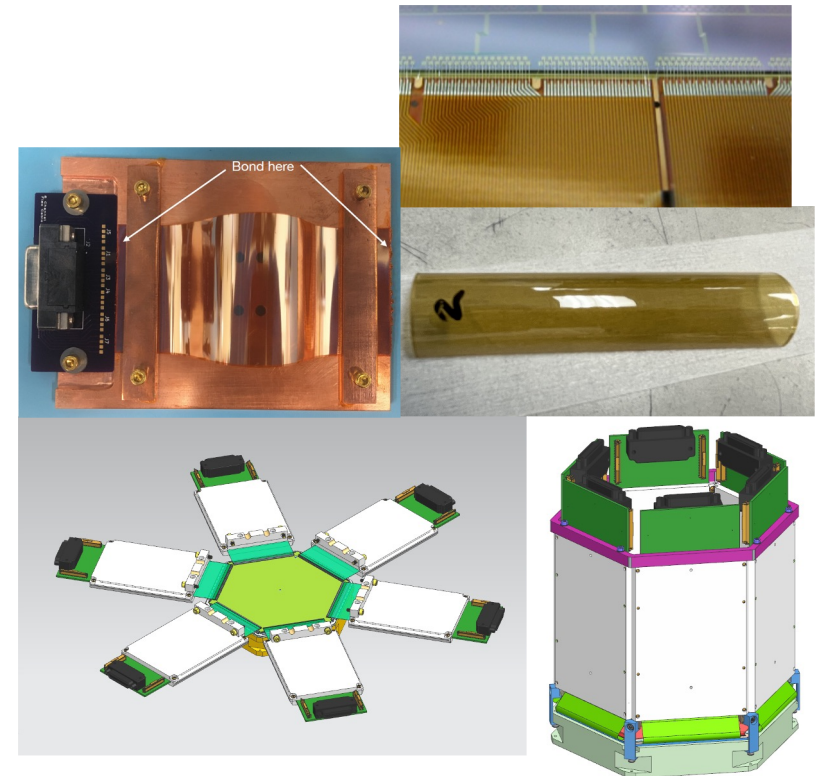


# Superconducting Flex

- Development led by CEA
- Production planned to be carried by two companies Hightec and Cicor/Microtech.
- Flexible
- Superconducting
- Low parasitic resistance ( $\ll 1\text{m}\Omega$ )
- High yield ( $\sim 100\%$ )

AI assisted **visual inspection** tool to be developed

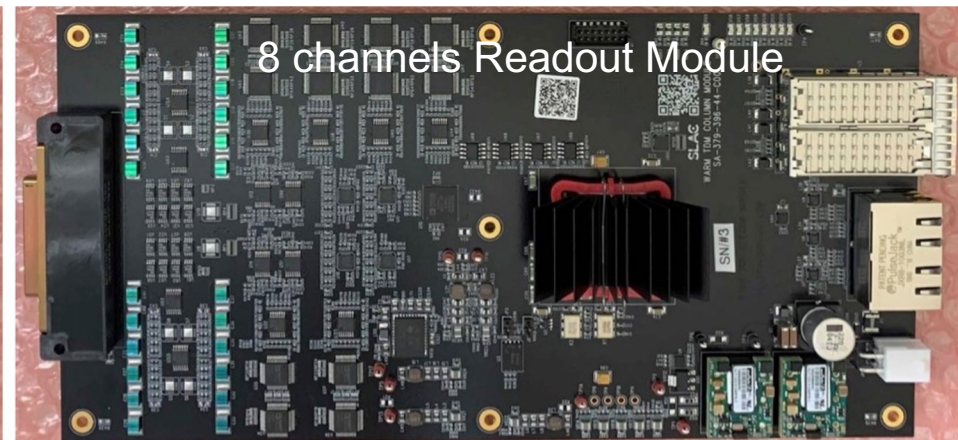
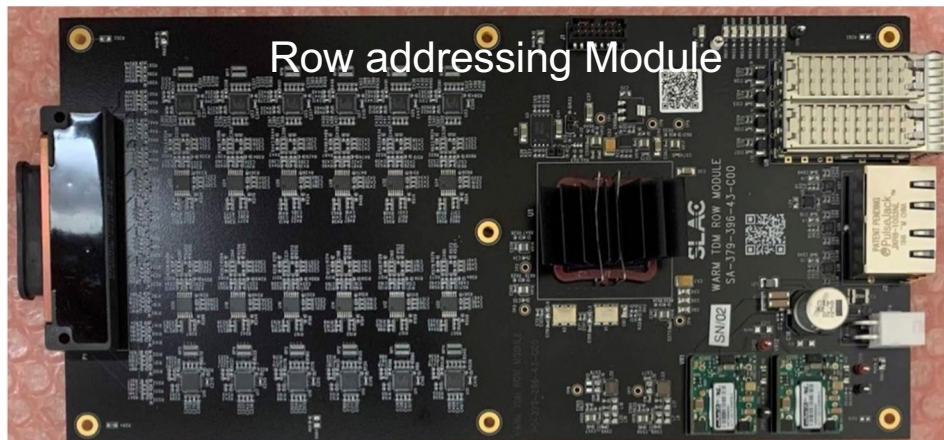
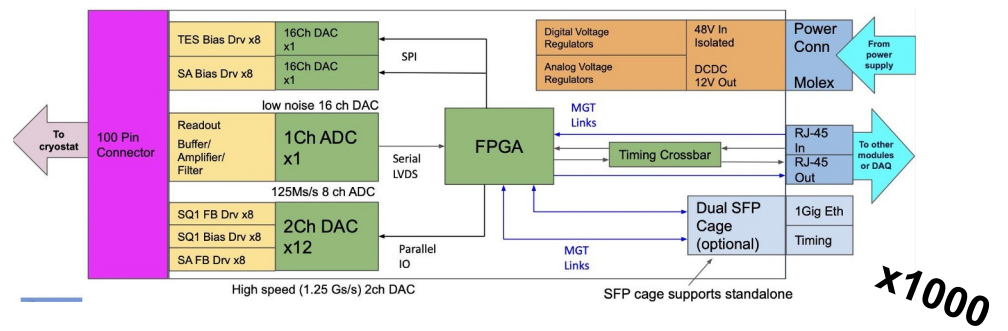
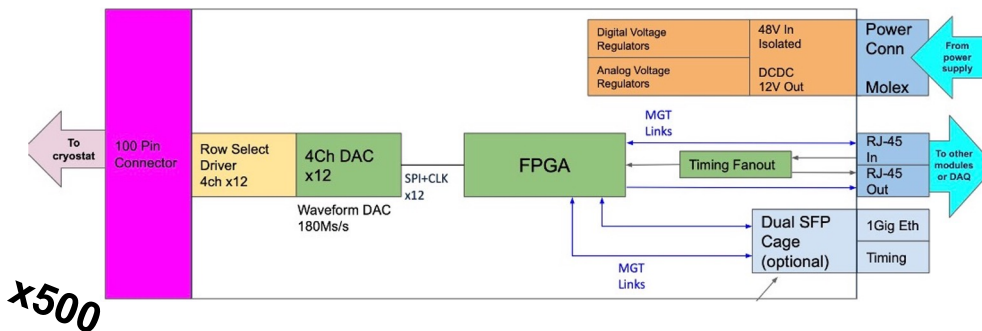
**Cryogenic tests** to be performed at APC/Cryo-MAT



CEA-Irfu: Xavier de la Broïse, Jean-Luc Sauvageot, Jean-Baptiste Melin, Etienne Burtin, Sotiris Loucatos  
CNRS-In2p3-APC: Damien Prêle, Manuel Gonzalez, Michel Piat, Jean-Pierre Thermeau

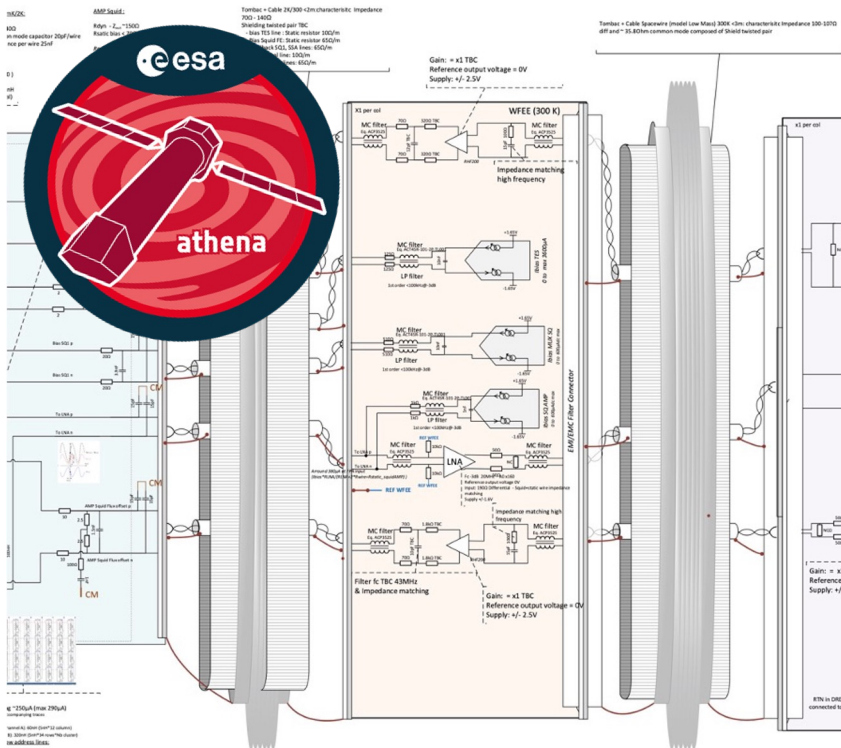
# Warm readout

This subsystem is under SLAC responsibility



# Warm readout background

Front-end readout ASIC family designed for ATHENA X-IFU



## Specific Integrated Circuit for the X-IFU Warm Front-End Electronics

Damien Prêle (APC, Paris) on behalf of the WFEE and X-IFU detection chain team.

The X-IFU (X-ray Integral Field Unit) instrument of the Athena mission is designed to operate with 3168 superconducting microcalorimeters (read out by Transition Edge Sensors - TES) cooled to 80 mK, providing an imaging spectrometer for X-ray astronomy. The unprecedented spectral resolution of 2.5 eV up to 7 keV requires low noise readout electronics. Located immediately outside the cryostat, the Warm Front End Electronics (WFEE) is a key component of the readout electronics.

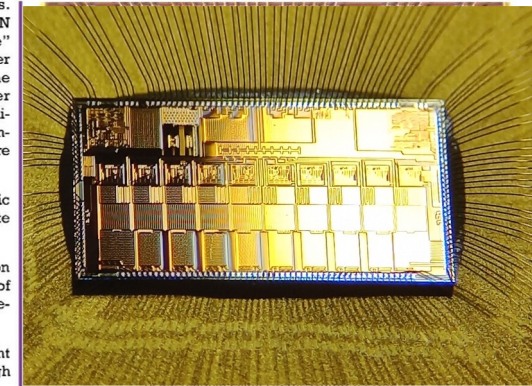
The WFEE amplifies the detection chain signal, adjusts the operating points of the cryogenic devices (Superconducting QUantum Interference Devices - SQUIDS), and feeds through the TES bias and feedback loop. Using Frequency Domain Multiplexing (FDM, see Athena Nugget #25 for more details), 40 microcalorimeters are read out per channel and 40 carriers between 1 to 5 MHz are injected to 40 sensors. As a result, the detected X-ray pulses are transposed into 40 different frequencies. Ultimately, about one hundred channels are needed for the full readout of the TES array.

To meet the energy resolution of the cryogenic sensors, the WFEE, like the whole readout chain, has to exhibit ultra-low noise and extremely small gain-drift. At the same time, the size, the mass, and the dissipation must be minimized as required for a space mission. For this reason, an Application-Specific Integrated Circuit (ASIC) has been designed for the WFEE. "350 nm BiCMOS SiGe" ASIC technology is used for the core of the WFEE. "350nm" corresponds to the minimum gate size of MOS transistors. "BiCMOS" means that both bipolar transistors and complementary (N and P) MOS transistors can be built using this technology. Finally, "SiGe" indicates that Silicon-Germanium alloy is used to make the base-emitter junction of the bipolar transistor. Such a hetero-junction increases the speed of the transistors allowing the design of a wide-band amplifier covering the frequency range of the carriers used for the FDM. The micro-photograph illustrates an ASIC chip design for the WFEE. Eight independent readout channels will be integrated on a chip of one square centimetre.

The noise degradation of WFEE is minimized by reducing any parasitic resistance and thanks to fine-tuning of the transistors biasing to operate in an optimal noise condition.

The gain drift is also a significant contributor to the energy resolution budget. At large time scale ( $> 1s$ ), the thermal drift is the main cause of electronic parameter shifts. The entire circuit is based on a specific design including thermal compensation techniques.

The WFEE with its custom designed ASIC is a compact, light-weight component with minimal power consumption and it delivers the high performance required for Athena's X-IFU readout electronics.



IFU	Project: ATHENA X-IFU	Ed: DID 1.2	Rev: 0
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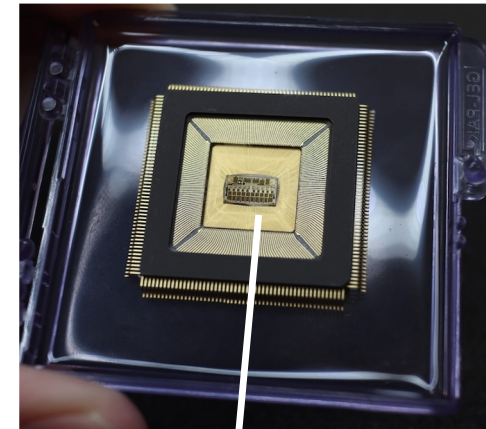
# Front-end readout daughter board

Drop-in integrated circuit for analog readout.  
Bias and amplification for 2 TDM columns.  
Initially developed for X-ray TES readout (ATHENA)  
**Fully differential, low noise and low thermal drift.**

Daughter board based on current package

- Fabricated
- **Delivered last week**
- First tests/adjustments currently done

2 x **LNA** 20 MHz 0.7 nV/ $\sqrt{\text{Hz}}$   
2 x DC DAC for **SQ1 bias**  
2 x DC DAC for **SSA bias**  
2 x DC DAC for **TES bias**  
DACs controlled through I2C



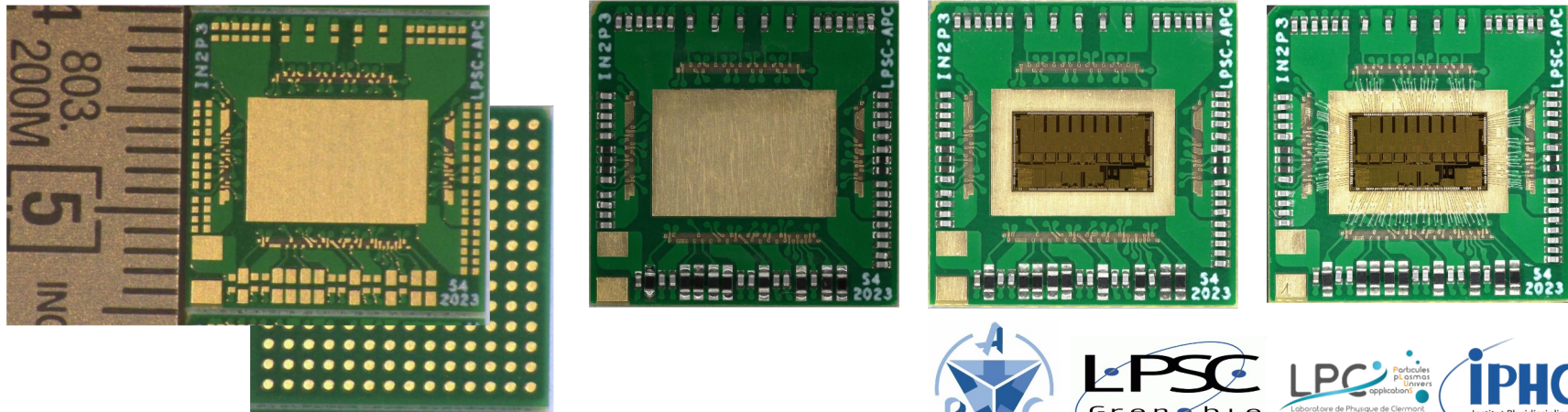
# Design of new compact BGA package

1.5 cm PCB with glued and bonded ASIC naked die and passive components

**Compact system in package** of the ASIC as a BGA\*  
In preparation for 4 ASICs integration in one board

\*Ball Grid Array - BGA : chip carrier, surface-mount packaging

Company	Work	Delay
PCB electronics (french company)	PCB Fabrication	4 weeks
LPC Clermont-Ferrand (IN2P3 Lab)	Soldering - Passive components	2 weeks
C4PI @IPHC (IN2P3 Lab)	wire bonding - Chip on Board	2 weeks
Itancia	Solder Bump	6 weeks







# Conclusions and way forward

- Strong **interest** of the CMB community on the CMB-S4 science and instrumental developments
- Readout contributions/activities for the **next three years formalized**
- **Cohesive effort to capitalize** the development for other CMB projects
- Strong **collaboration with SLAC**
- **First French CMB-S4 hardware delivered last week**
- We need to **start thinking about the production phase**